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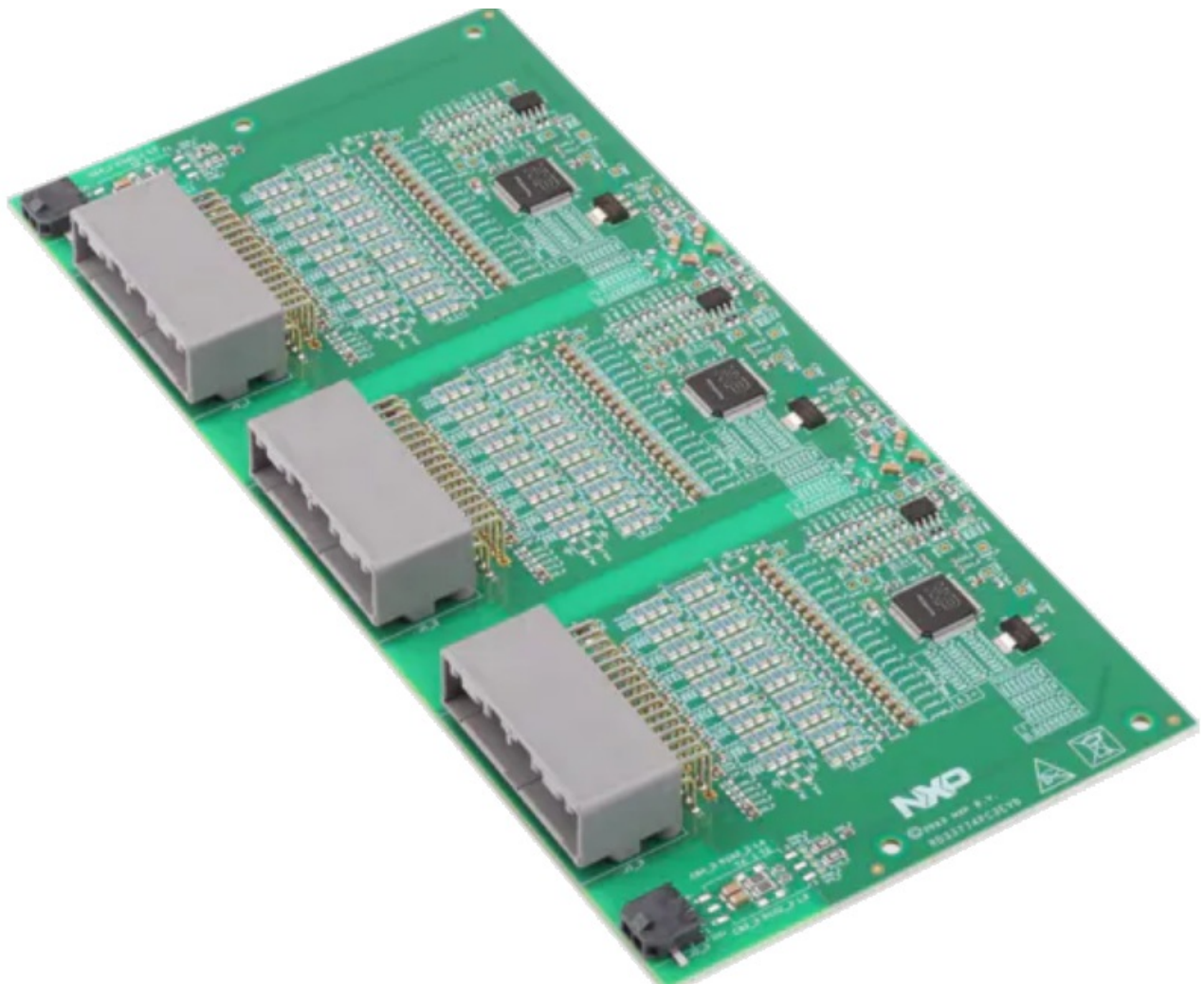MC33774A Cell
Monitoring Unit

NXP MC33774A Cell Monitoring Unit User Manual

Contents

NXP MC33774A Cell Monitoring Unit

Specifications

- **Product Name**: RDBESS774A1EVB
- **Features:** Three MC33774A battery-cell controller integrated circuits
- **Manufacturer:** NXP Semiconductors
- **Platform:** Analog product development board
- **Supported Technologies:** Analog, mixed-signal, and power solutions

Product Usage Instructions

Finding Kit Resources and Information
To access resources and information related to the RDBESS774A1EVB evaluation board:

1. Visit **http://www.nxp.com/RDBESS774A1EVB**
2. Locate the Jump To navigation feature on the left side of the window on the Overview tab
3. Select the Getting Started link
4. Review each entry in the Getting Started section
5. Download any required assets by clicking the linked title

After reviewing the Overview tab, explore other related tabs for more detailed information. Make sure to review and follow the setup instructions provided in the user guide after downloading the necessary files.

Document information

Information	Content
Keywords	MC33774A, HVBESS cell monitoring unit, centralized evaluation board
Abstract	This user manual describes the RDBESS774A1EVB. The board features three MC33774 A battery cell controller ICs. With the evaluation board (EVB), the key functions of the MC 33774A can be explored.

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- NXP provides the product under the following conditions:
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- The product provided may not be complete in terms of required design, marketing, and or manufacturing related protective considerations, including product safety measures typically found in the end device incorporating the product. Due to the open construction of the product, it is the responsibility of the user to take all appropriate precautions for electric discharge. In order to minimize risks associated with the customers' applications, adequate design and operating safeguards must be provided by the customer to minimize inherent or procedural hazards. For any safety concerns, contact NXP sales and technical support services.

Introduction

- This user manual describes the RDBESS774A1EVB. The board features three MC33774A battery-cell controller integrated circuits (IC).
- NXP analog product development boards provide an easy-to-use platform for evaluating NXP products. These development boards support a range of analog, mixed-signal, and power solutions. These boards incorporate monolithic ICs and system-in-package devices that use proven high-volume technology.

Finding kit resources and information on the NXP website

NXP Semiconductors provides online resources for this evaluation board and its supported device(s) on **http://www.nxp.com**.
The information page for the RDBESS774A1EVB evaluation board is at **http://www.nxp.com/RDBESS774A1EVB**. The information page provides overview information, documentation, software and tools, parametric, ordering information, and a Getting Started tab. The Getting Started tab provides quick-reference information applicable to using the RDBESS774A1EVB evaluation board, including the downloadable assets referenced in this document.
The tool summary page for RDBESS774A1EVB is the HVBESS Cell Monitoring Unit (CMU). The overview tab on this page provides an overview of the device, a list of device features, a description of the kit contents, links to supported devices, and a Getting Started section.

The Getting Started section provides information applicable to using the RDBESS774A1EVB.

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3. Select the Getting Started link.
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- **Buy**/**Parametrics**: Purchase the product and view the product parametrics.

After downloading files, review each file, including the user guide, which includes setup instructions.

Getting ready

Working with the RDBESS774A1EVB requires the kit contents, additional hardware, and a Windows PC workstation with installed software.

Kit contents
The kit contents include:

- Assembled and tested evaluation board/module in antistatic bag
- One cell terminal cable
- One transformer physical layer (TPL) cable

Additional hardware
To use this kit, the following hardware is required:

- A 4-cell to 18-cell battery pack or a battery-pack emulator, such as BATT-18CEMULATOR[1].
- A TPL communication system. If a user-specific system is not available, the evaluation setup or the 1500 V high-voltage battery energy storage system (HVBESS) reference design can be used.
    - The 1500 V HVBESS reference design consists of the HVBESS battery management unit (RD-BESSK358BMU [2]) and the 1500 V HVBESS battery junction box (RDBESS772BJBEVB [3]). For the 1500 V HVBESS reference design, a graphical user interface (GUI) is available.
    - The evaluation setup consists of the FRDM665SPIEVB (EVB for MC33665A)[4] with the S32K3X4EVB-T172 (S32K3X4 EVB)[5]
    - For the evaluation setup, EvalGUI 7[6] is available.

Getting to know the hardware

Kit overview
The RDBESS774A1EVB is a hardware evaluation tool supporting the NXP MC33774A device. The RDBESS774A1EVB implements three MC33774A battery cell controller ICs. The MC33774A is a battery-cell controller that monitors up to 18 Li-ion battery cells. It is designed for use in both automotive and industrial

applications. The device performs analog-to-digital conversions (ADC) on the differential cell voltages. It is also capable of temperature measurements and can forward communication via an I2C-bus to other devices. The RDBESS774A1EVB is an ideal platform for rapid prototyping of MC33774A-based applications that involve voltage and temperature sensing. The RDBESS774A1EVB measures the pressure of the battery module using the onboard FXPS7250A4ST1 pressure sensor. The RDBESS774A1EVB converts the battery module voltage to 12 V using the TEA1721AT/N1,118 flyback controller, then converts the 12 V to

V to supply the pressure sensor.

The RDBESS774A1EVB uses inductive isolation for offboard communication. The galvanic isolation for onboard communication is established via capacitors.
The RDBESS774A1EVB is also used as part of the 1500 V HVBESS reference design consisting of the HVBESS battery management unit (BMU)[2] and the 1500 V HVBESS battery junction box (BJB)[3].
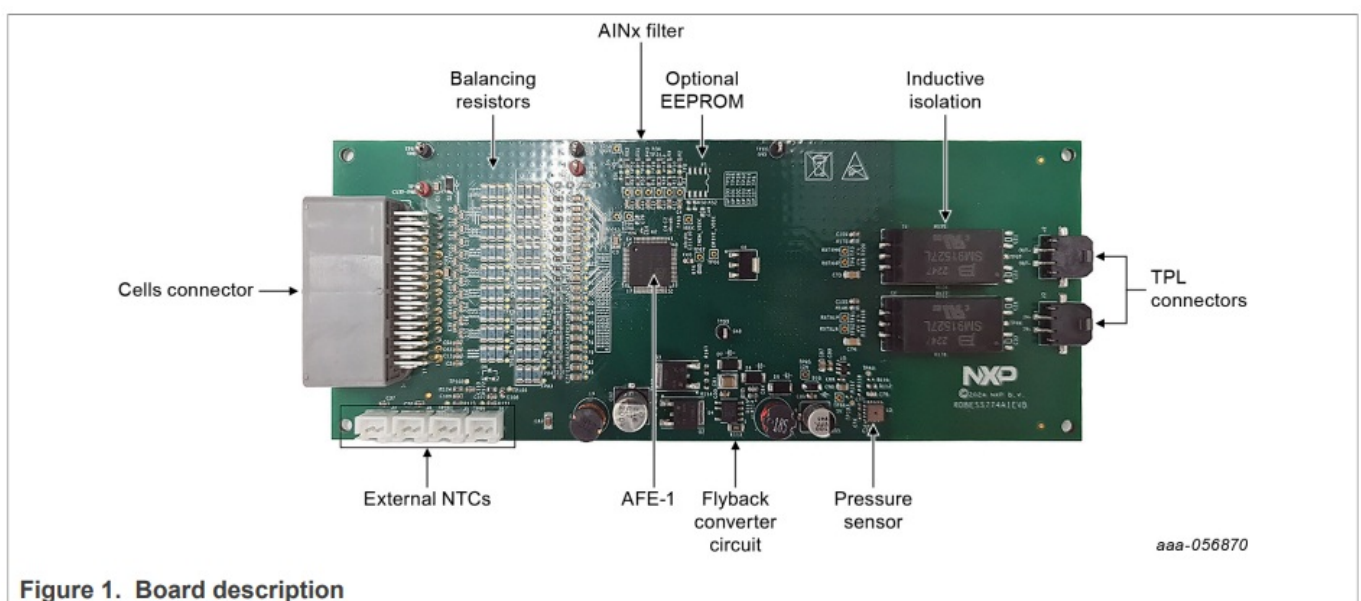
Board description

Figure 1. Board description

With the RDBESS774A1EVB, the user can explore all functions of the MC33774A battery-cell controller.

Board features
The main features of RDBESS774A1EVB are:

- Reference design with three MC33774A, showing an optimized bill of materials (BOM) as outlined in the data sheet
- Capacitive isolation for onboard communication
- Based on NXP core layout for MC33774A; core layout is used for NXP internal electromagnetic compatibility (EMC) and hotplug tests
- Four-layer board, all components are assembled only on the top side
- Cell electrostatic discharge (ESD) capacitors package 0805
- 805 packages used for all signals with a voltage higher than approximately 25 V
- Three 1206 surface mounted device (SMD) resistors per balancing channel for individual cell-voltage balancing
- All eight external thermistor inputs are available
- Onboard high-performance, high-precision absolute pressure sensor
- Placeholder for I2C-bus EEPROM

- Can be used together with the 1500 V HVBESS reference design or the evaluation setup

Pressure sensor power circuit
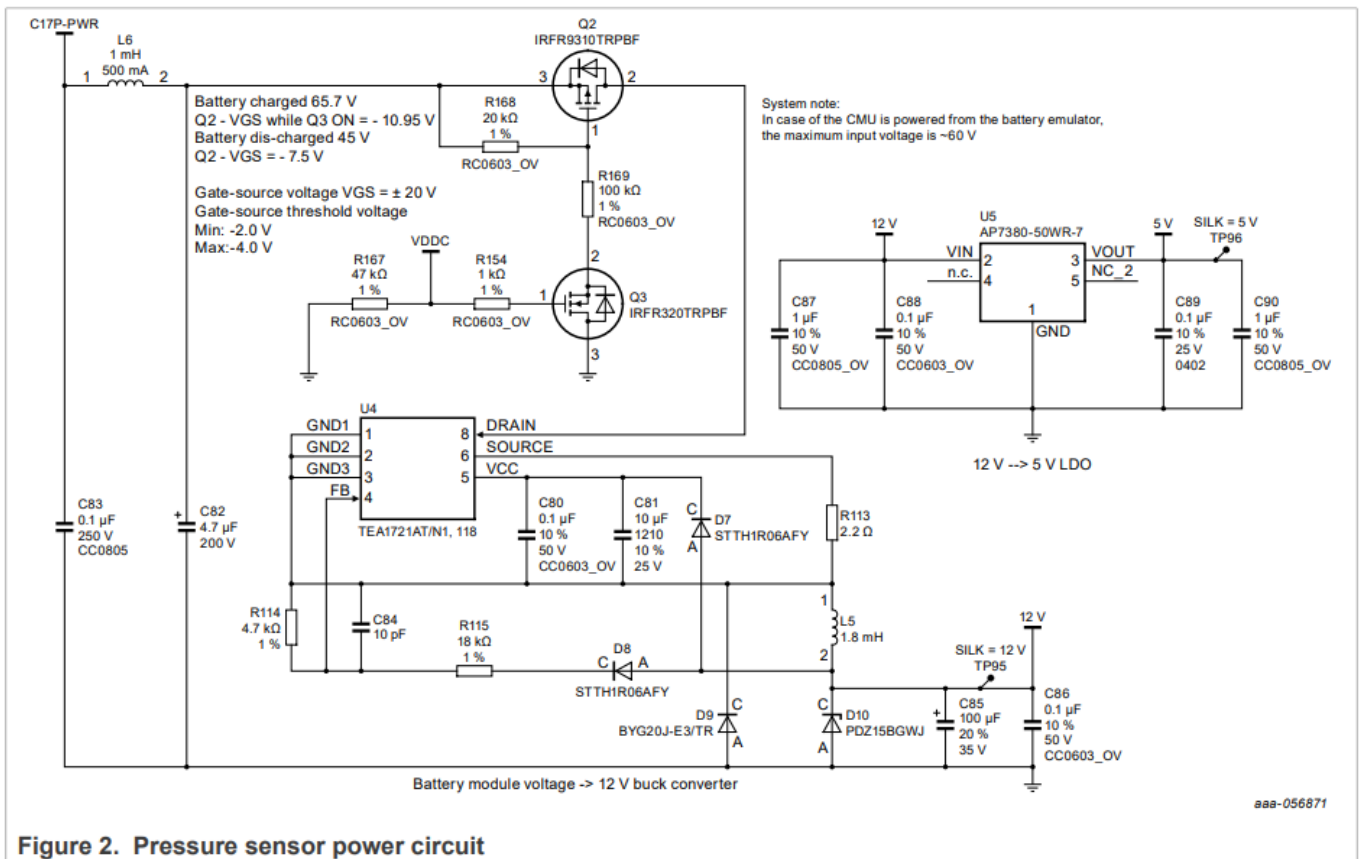
Figure 2. Pressure sensor power circuit

The RDBESS774A1EVB measures the pressure of the battery module using the onboard FXPS7250A4ST1 pressure sensor. The RDBESS774A1EVB converts the battery module voltage to 12 V using the TEA1721AT/N1,118 flyback controller then converts the 12 V to 5 V to supply the pressure sensor.

The RDBESS774A1EVB is designed to be used with a battery module that consists of 18 LFP cells in series so the nominal battery module voltage will be around 58 V. If an 18-cell battery emulator board, BATT-18EMULATOR [1] to power the RDBESS774A1EVB board, there is nothing to change.
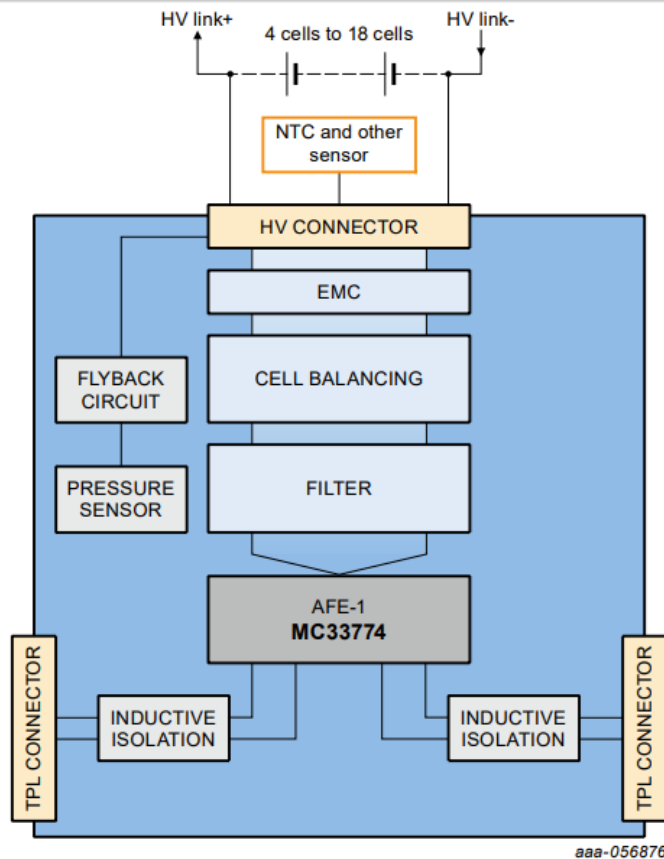
Block diagram

Figure 3. Block diagram

Kit featured components

Connectors
The cells and NTC connections are available on J1. See Figure 4. Additional NTCs connections are available on J4, J5, J6, and J7.

Cell0 is connected between C0M(cell0M) and C1M(cell0P); Cell1 is connected between C1M(cell1M) and C2M(cell1P), and so on … Cell17 is connected between C17M (cell17M) and C17P (cell17P). C17P-PWR and GND (pin21) are used to supply the AFE and are separated from C17P and C0M respectively, to avoid any voltage drop due to the EVB current consumption.

Optional external 10 kΩ NTCs can be connected between each NTCx terminal and one GND terminal.

- Connector type: JAE MX34032NF2 (32 pins/right angle version)
- Corresponding mate connector reference: MX34032SF1
- Crimp reference for the mate connector: M34S7C4F1c
- Additional NTCs connector type is JST B2B-XH-A(LF)(SN) (two pins/top mount version)
- Corresponding mate connector reference: XHP-2
- Crimp reference for the mate connector: SXH-001T-P0.6N
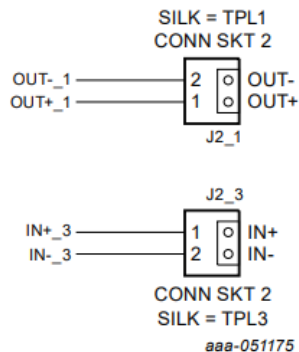
NXP Semiconductors

RDBESS774A1EVB featuring the MC33774A battery cell controller integrated circuit
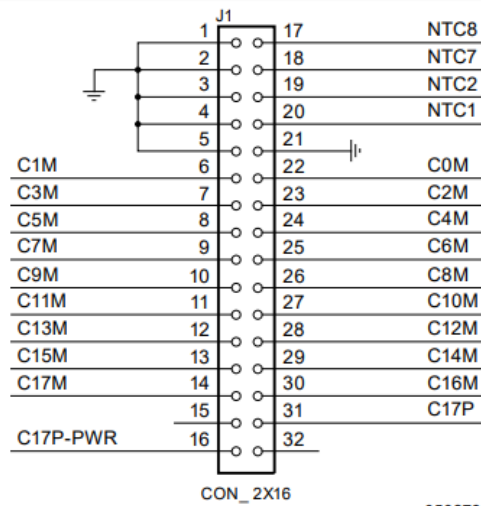
Figure 4. Pinout cells connector
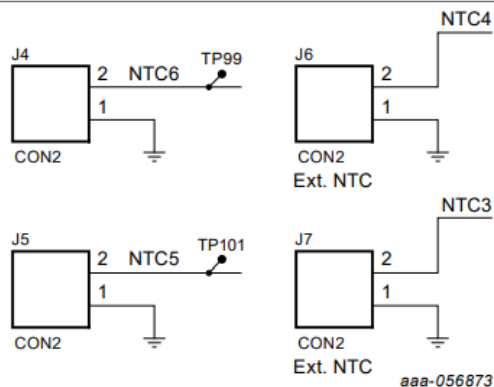
Figure 5. Additional NTC connectors

Figure 6. TPL connectors

The TPL connections are available on J2 and J3. See Figure 6

- Connector type: Molex Micro-fit 3.0, 43650-0213
- Corresponding mate connector reference: 0436450200
- Crimp reference for the mate connector: 0436450201 Figure 1 shows the location of connectors on the board.

Kit featured components

- The MC33774A is a battery-cell controller IC designed to monitor battery characteristics, such as voltage and temperature. The MC33774A contains all the circuit blocks necessary to perform battery-cell voltage, cell-temperature measurement, and integrated cell balancing. The device supports the following functions:
  - AEC-Q100 grade 1 qualified: –40 °C to 125 °C ambient temperature range

- ○ ISO 26262 ASIL D support for cell-voltage and cell-temperature measurements from the host MCU to the cell
- Cell-voltage measurement
  - ○ 4 cells to 18 cells per device
  - ○ Supports bus bars voltage measurement with 5/-3 V input voltage
  - ○ 16-bit resolution and ±1 mV typical measurement accuracy with ultra-low long-term drift
  - ○ 136 μs synchronicity of cell-voltage measurements
  - ○ Integrated configurable digital filter
- External temperature and auxiliary voltage measurements
  - ○ One analog input for absolute measurement, 5 V input range
  - ○ Eight analog inputs configurable as absolute or ratiometric, 5 V input range
  - ○ 16-bit resolution and ±5 mV typical measurement accuracy
  - ○ Integrated configurable digital filter
- Module voltage measurement
  - ○ 9.6 V to 81 V input range
  - ○ 16-bit resolution and 0.3 % measurement accuracy
  - ○ Integrated configurable digital filter
- Internal measurement
  - ○ Two redundant internal temperature sensors
  - ○ Supply voltages
  - ○ External transistor current
- Cell-voltage balancing
  - ○ 18 internal balancing field effect transistors (FET), up to 150 mA average with 0.5 Ω RDSon per channel (typ.)
  - ○ Support for simultaneous passive balancing of all channels with automatic odd/even sequence
  - ○ Global balancing timeout timer
  - ○ Timer-controlled balancing with individual timers with 10 s resolution and up to 45 h duration
  - ○ Voltage-controlled balancing with global and individual undervoltage thresholds
  - ○ Temperature-controlled balancing; if balancing resistors are in overtemperature, balancing is interrupted
  - ○ Configurable pulse width modulation (PWM) duty cycle balancing
  - ○ Automatic pause of balancing during measurement with configurable filter settling time
  - ○ Configurable delay of the start of balancing after transition to sleep
  - ○ Automatic discharge of the battery pack (emergency discharge)
  - ○ Constant current cell balancing to compensate the balancing current variation due to cell-voltage variation
  - ○ Deep sleep mode (15 μA typ.)
- Battery module pressure monitoring
  - ○ Absolute pressure range: 20 kPa to 250 kPa
  - ○ Operating temperature range: –40 °C to 130 °C
  - ○ Analog output for monitoring of the absolute pressure signal
  - ○ Pressure transducer and digital signal processor (DSP)
  - ○ Internal self-test
- Capacitance to voltage converter with antialiasing filter

- Sigma-delta ADC plus sinc filter
- 800 Hz or 1000 Hz low-pass filter for absolute pressure
- Lead-free, 16-pin HQFN, 4 mm x 4 mm x 1.98 mm package
    - I2C-bus master interface to control external devices, for example, EEPROMs and security ICs
    - Configurable alarm output
    - Cyclic wake-up to supervise the pack during sleep and balancing
    - Capability to wake up the host MCU via daisy chain in a fault event
- Host interface supporting SPI or transformer physical layer 3 (TPL3)
    - 2 Mbit data rate for TPL3 interface
    - 4 Mbit data rate for SPI
- TPL3 communication supports
    - Two-wire daisy chain with capacitive and inductive isolation
    - Protocol supporting up to six daisy chains and 62 nodes per chain
- Unique device ID
- Operation modes
    - Active mode (12 mA typ.)
    - Sleep mode (60 µA typ.)

Schematic, board layout, and bill of materials
The schematic, board layout, and bill of materials for the RDBESS774A1EVB evaluation board are available at
http://www.nxp.com/RDBESS774A1EVB.

Accessory boards

NXP 1500 V HVBESS reference design
The NXP 1500 V HVBESS reference design is a scalable SIL 2 architecture for high-voltage applications,
composed of three modules: BMU, CMU, and BJB.

RDBESS774A1EVB featuring the MC33774A battery cell controller integrated circuit
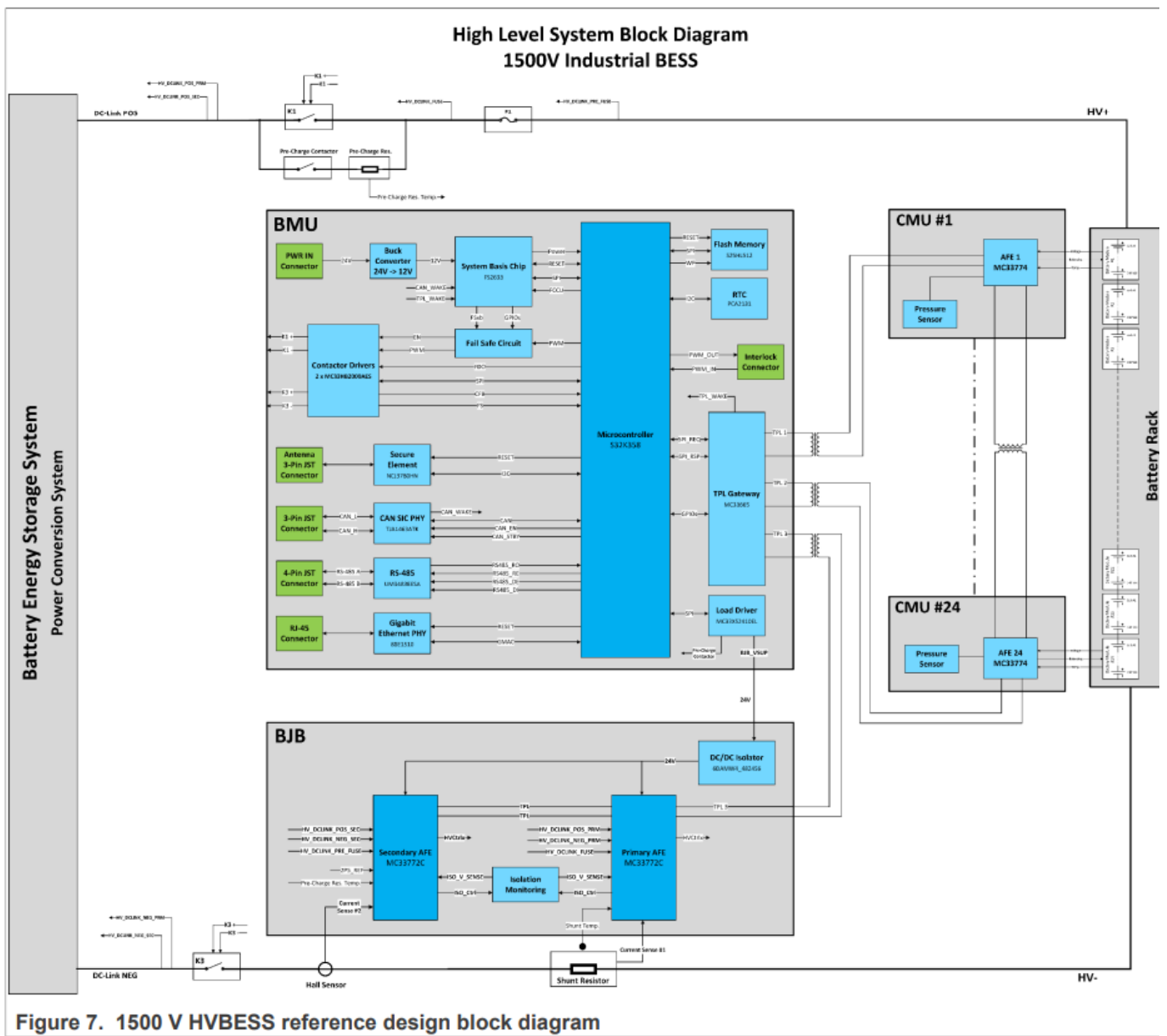
Figure 7. 1500 V HVBESS reference design block diagram

FRDM665SPIEVB

- The RDBESS774A1EVB kit is designed for use with the FRDM665SPIEVB[4]. The FRDM665SPIEVB is an evaluation board for the MC33665A, a gateway router that can route TPL messages from the MCU to four different TPL ports. It is designed for use in both automotive and industrial applications. The device can route both TPL2 and TPL3 messages. The FRDM665SPIEVB is an ideal board for rapid prototyping of the MC33665A for SPI interface to an MCU. The onboard TPL interface for four TPL ports has transformer isolation.
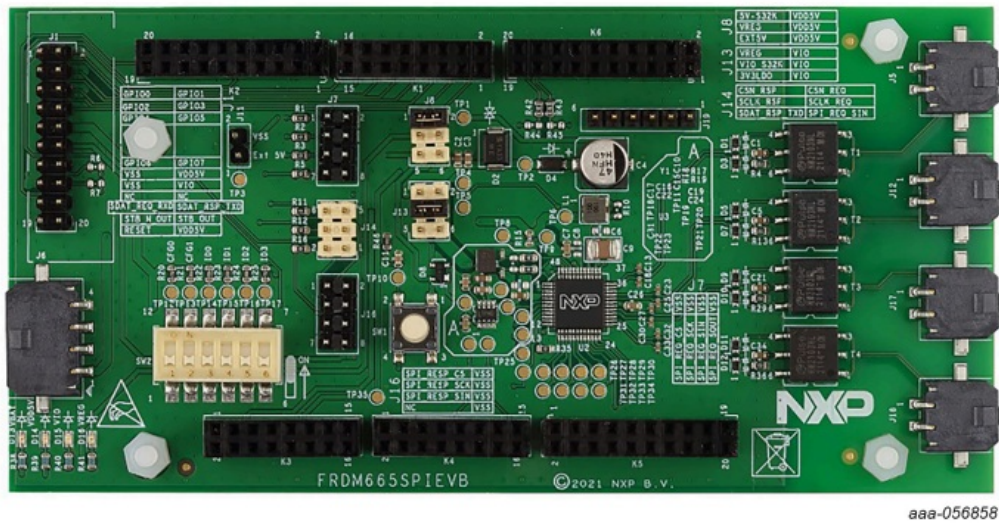
Figure 8. FRDM665SPIEVB

S32K3X4EVB-T172

The S32K3X4EVB[6] provides the control signals for the FRDM665SPIEVB.

Figure 9. S32K3X4 evaluation board

Configuring the hardware

Battery emulator connection

A minimum of four cells and a maximum of 18 cells can be monitored by one MC33774A. NXP provides an 18-cell battery emulator board, BATT-18EMULATOR [1]. This board provides an intuitive way to change the voltage across any of the 18 cells of an emulated battery pack. The board RDBESS774A1EVB can be connected to an 18-cell battery emulator board using the connectors J2 and J3, with the provided supply cable. See Figure 10.
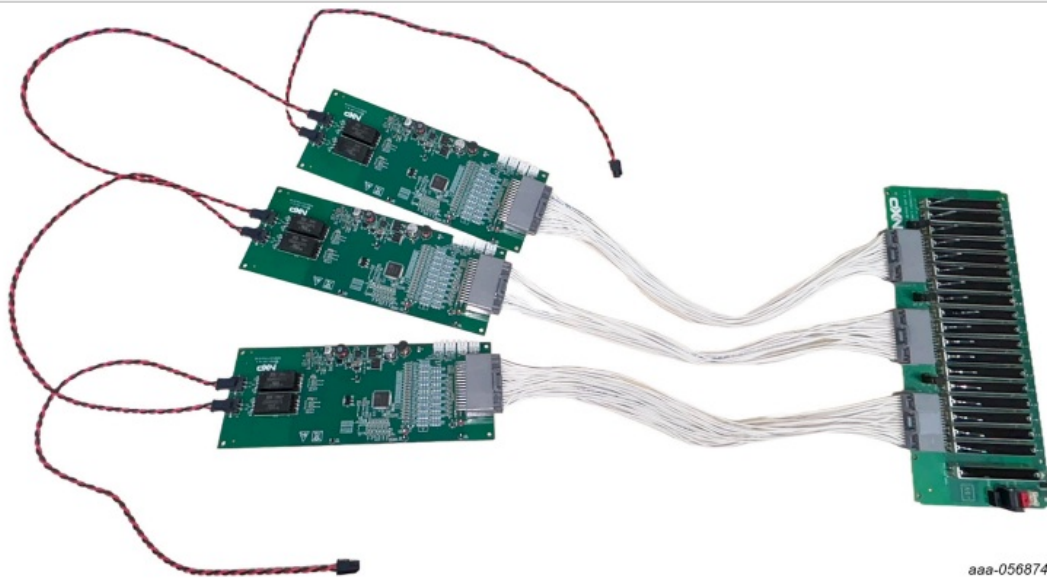
Figure 10. Battery emulator connection

TPL communication connection

- In a high-voltage isolated application with a daisy chain configuration, up to 63 RDBESS774A1EVB boards may be connected.
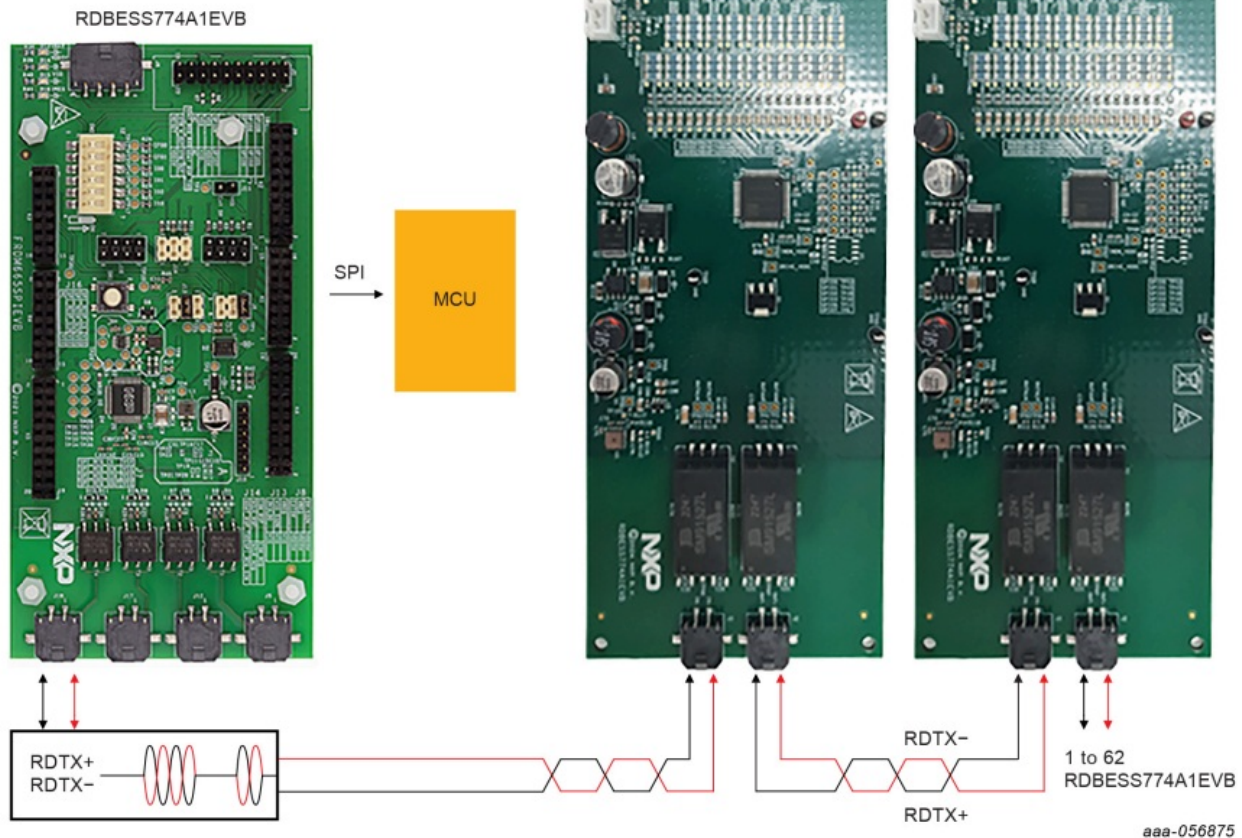- The TPL connections use the COMM connectors J1 and J2 of the FRDM665SPIEVB[4] and J2 and J3 of the RDBESS774A1EVB.

Figure 11. FRDM665SPIEVB setup

References

1. Tool summary page for battery emulators — BATT-18EMULATOR
2. RD-BESSK358BMU HVBESS Battery Management Unit (BMU) https://https://www.nxp.com/part/RD-K358BMU
3. RDBESS772BJBEVB HVBESS Battery Junction Box (BJB) **https://www.nxp.com/design/designs/HVBESS-battery-junction-box-bjb**: RD772BJBTPL8EVB
4. Tool summary page for evaluation board for MC33665A with SPI and TPL Communication —FRDM665SPIEVB
5. Tool summary page for S32K3X4 evaluation board — **https://www.nxp.com/design/development-boards/automotive-development-platforms/s32k-mcu-platforms/s32k3x4evb-t172-evaluation-board-for-automotive-general-purpose**:S32K3X4EVB-T172
6. Tool summary page for RDBESS774A1EVB evaluation board — **https://www.nxp.com/**RDBESS774A1EVB

Revision history

Table 1. Revision history

Document ID	Release date	Description
UM12147 v.1.0	20 September 2024	Initial version

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- **Date of release:** 20 September 2024
- **Document identifier**: UM12147

FAQ

What is the purpose of the RDBESS774A1EVB evaluation board?
The RDBESS774A1EVB is designed for engineering development and evaluation purposes. It features three MC33774A battery-cell controller integrated circuits for exploring key functions of the MC33774A.

Where can I find additional documentation and software for the RDBESS774A1EVB?
You can access documentation, software, tools, and other resources related to the RDBESS774A1EVB on the NXP website at : **http://www.nxp.com/RDBESS774A1EVB**.

Documents / Resources

UM12147 RDBESS774A1EVB Featuring the MC33774A battery-cell controller integrated circuit Rev 1.0 — 26 September 2024 User manual NXP	**NXP MC33774A Cell Monitoring Unit** [pdf] User Manual RDBESS774A1EVB, MC33774A, MC33774A Cell Monitoring Unit, MC33774A, Cell Monitoring Unit, Monitoring Unit, MC33774A Unit

References

- **User Manual**